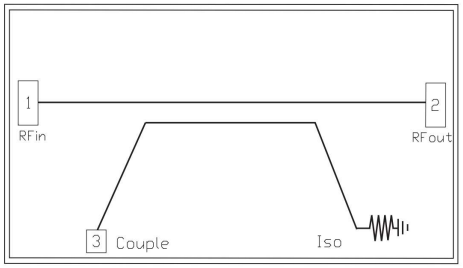
Performance

- Frequency: 12~20GHz
- Coupling: 35dB
- Coupling Flatness: 2dB
- Chip size: 2.0*2.0*0.1mm

Function Diagram

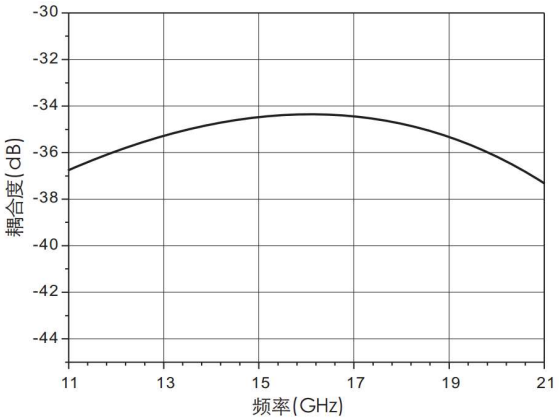


Electrical Specifications (Ta=+25℃, 50Ω system)

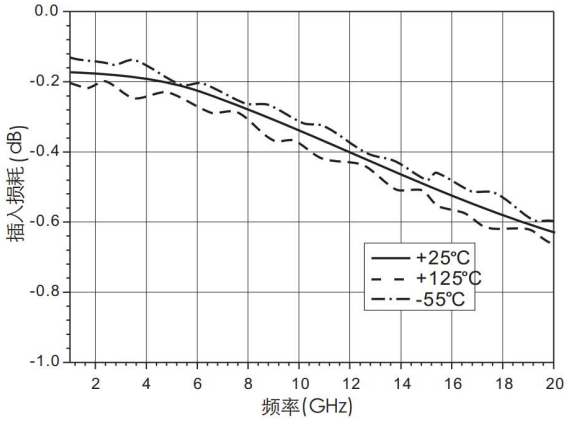
Parameter	Min	Typical	Max	Unit
Frequency Range		12~20		GHz
Coupling	34	35	36	
Insertion Loss	0.4	0.55	0.7	dB
Input Return loss	20	25	-	dB
Thru Output Return loss	11	23	-	dB
Coupling Output Return loss	28	30	-	dB

Test Curves (Die chip + Bonding line test)

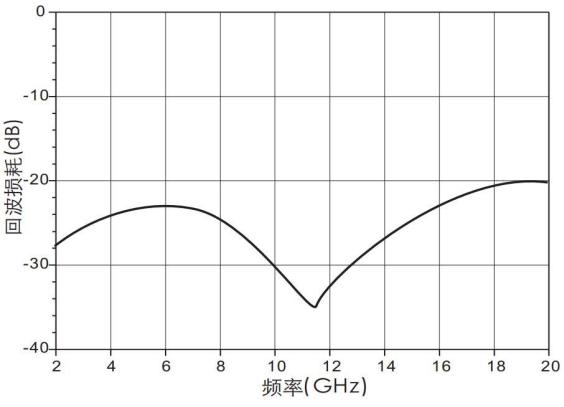
Coupling vs. Freq



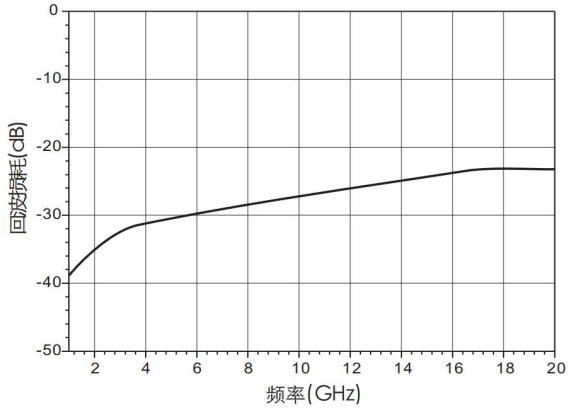
Insertion loss vs. Freq



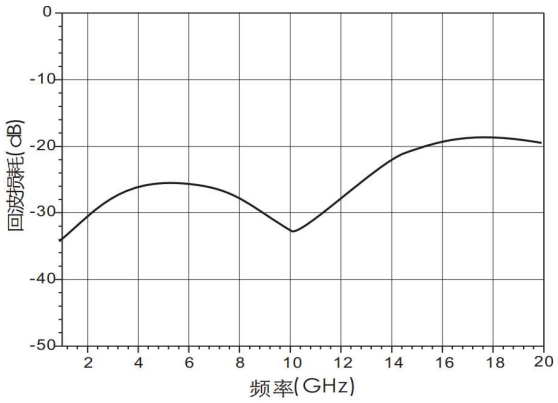
Input Return Loss vs. Freq



Thru output Return loss vs. Freq



Coupling Output Return Loss

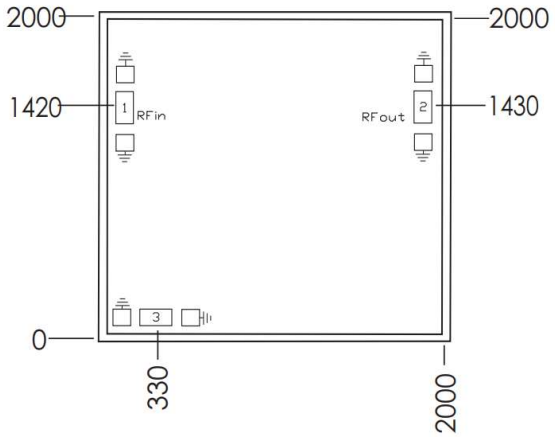


Absolute Rating

Storage Temperature	-65~+150℃
Operating Temperature	-55~+125℃
Max Input Power	4W
Static Protection (HBM)	Class 1A

ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

Outline Size



Note:

1. Unit: um
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated,
   Pad size: 100*100(um)
5. Don't bonding on thru holds
6. Tolerance: ±50um

Bonding Pads Definition

Number	Symbol	Description
1	RFin	RF input port, 50ohm
2	RFout	RF output port, 50 ohm
3,4	Couple	Coupling output, 50ohm

Application